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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	8272
Number of Logic Elements/Cells	74448
Total RAM Bits	6045696
Number of I/O	964
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp70-6ff1517i

- Programmable Receiver Equalization
- Internal AC Coupling
- On-Chip 50Ω Termination
  - Eliminates the need for external termination resistors
- Pre- and Post-Driver Serial and Parallel TX-to-RX Internal Loopback Modes for Testing Operability
- Programmable Comma Detection
  - Allows for any protocol
  - Allows for detection of any 10-bit character
- 8B/10B and 64B/66B Encoding Blocks

RocketIO Transceiver Features (All Except XC2VPX20 and XC2VPX70)

- Full-Duplex Serial Transceiver (SERDES) Capable of Baud Rates from 600 Mb/s to 3.125 Gb/s
- 100 Gb/s Duplex Data Rate (20 Channels)
- Monolithic Clock Synthesis and Clock Recovery (CDR)
- Fibre Channel, 10G Fibre Channel, Gigabit Ethernet, 10 Gb Attachment Unit Interface (XAUI), and Infiniband-Compliant Transceivers
- 8-, 16-, or 32-bit Selectable Internal FPGA Interface
- 8B /10B Encoder and Decoder (optional)
- 50Ω /75Ω on-chip Selectable Transmit and Receive Terminations
- Programmable Comma Detection
- Channel Bonding Support (from 2 to 20 Channels)
- Rate Matching via Insertion/Deletion Characters
- Four Levels of Selectable Pre-Emphasis
- Five Levels of Output Differential Voltage
- Per-Channel Internal Loopback Modes
- 2.5V Transceiver Supply Voltage

PowerPC RISC Processor Block Features (All Except XC2VP2)

- Embedded 300+ MHz Harvard Architecture Block
- Low Power Consumption: 0.9 mW/MHz
- Five-Stage Data Path Pipeline
- Hardware Multiply/Divide Unit
- Thirty-Two 32-bit General Purpose Registers
- 16 KB Two-Way Set-Associative Instruction Cache
- 16 KB Two-Way Set-Associative Data Cache
- Memory Management Unit (MMU)
  - 64-entry unified Translation Look-aside Buffers (TLB)
  - Variable page sizes (1 KB to 16 MB)
- Dedicated On-Chip Memory (OCM) Interface
- Supports IBM CoreConnect™ Bus Architecture
- Debug and Trace Support
- Timer Facilities

Virtex-II Pro Platform FPGA Technology (All Devices)

- SelectRAM+ Memory Hierarchy
  - Up to 8 Mb of True Dual-Port RAM in 18 Kb block SelectRAM+ resources
  - Up to 1,378 Kb of distributed SelectRAM+ resources
  - High-performance interfaces to external memory
- Arithmetic Functions
  - Dedicated 18-bit x 18-bit multiplier blocks
  - Fast look-ahead carry logic chains
- Flexible Logic Resources
  - Up to 88,192 internal registers/latches with Clock Enable
  - Up to 88,192 look-up tables (LUTs) or cascadable variable (1 to 16 bits) shift registers
  - Wide multiplexers and wide-input function support
  - Horizontal cascade chain and Sum-of-Products support
  - Internal 3-state busing
- High-Performance Clock Management Circuitry
  - Up to twelve Digital Clock Manager (DCM) modules
    - Precise clock de-skew
    - Flexible frequency synthesis
    - High-resolution phase shifting
  - 16 global clock multiplexer buffers in all parts
- Active Interconnect Technology
  - Fourth-generation segmented routing structure
  - Fast, predictable routing delay, independent of fanout
  - Deep sub-micron noise immunity benefits
- SelectIO™-Ultra Technology
  - Up to 1,164 user I/Os
  - Twenty-two single-ended standards and ten differential standards
  - Programmable LVCMOS sink/source current (2 mA to 24 mA) per I/O
  - XCITE Digitally Controlled Impedance (DCI) I/O
  - PCI / PCI-X support (1)
  - Differential signaling
    - 840 Mb/s Low-Voltage Differential Signaling I/O (LVDS) with current mode drivers
    - On-chip differential termination
    - Bus LVDS I/O

1. Refer to XAPP653 for more information.

implemented. In system mode, a Virtex-II Pro device will continue to function while executing non-test Boundary-Scan instructions. In test mode, Boundary-Scan test instructions control the I/O pins for testing purposes. The Virtex-II Pro Test Access Port (TAP) supports BYPASS, PRELOAD, SAMPLE, IDCODE, and USERCODE non-test instructions. The EXTEST, INTEST, and HIGHZ test instructions are also supported.

Configuration

Virtex-II Pro / Virtex-II Pro devices are configured by loading the bitstream into internal configuration memory using one of the following modes:

- Slave-serial mode
- Master-serial mode
- Slave SelectMAP mode
- Master SelectMAP mode
- Boundary-Scan mode (IEEE 1532)

A Data Encryption Standard (DES) decryptor is available on-chip to secure the bitstreams. One or two triple-DES key sets can be used to optionally encrypt the configuration data.

The Xilinx System Advanced Configuration Enviornment (System ACE) family offers high-capacity and flexible solution for FPGA configuration as well as program/data storage for the processor. See **DS080**, *System ACE CompactFlash Solution* for more information.

Readback and Integrated Logic Analyzer

Configuration data stored in Virtex-II Pro / Virtex-II Pro configuration memory can be read back for verification. Along with the configuration data, the contents of all flip-flops and latches, distributed SelectRAM+, and block SelectRAM+ memory resources can be read back. This capability is useful for real-time debugging.

The Xilinx ChipScope Integrated Logic Analyzer (ILA) cores and Integrated Bus Analyzer (IBA) cores, along with the ChipScope Pro Analyzer software, provide a complete solution for accessing and verifying user designs within Virtex-II Pro devices.

IP Core and Reference Support

Intellectual Property is part of the Platform FPGA solution. In addition to the existing FPGA fabric cores, the list below shows some of the currently available hardware and software intellectual properties specially developed for Virtex-II Pro / Virtex-II Pro X by Xilinx. Each IP core is modular, portable, Real-Time Operating System (RTOS) independent, and CoreConnect compatible for ease of design migration. Refer to **www.xilinx.com/ipcenter** for the latest and most complete list of cores.

Hardware Cores

- Bus Infrastructure cores (arbiters, bridges, and more)
- Memory cores (DDR, Flash, and more)
- Peripheral cores (UART, IIC, and more)
- Networking cores (ATM, Ethernet, and more)

Software Cores

- Boot code
- Test code
- Device drivers
- Protocol stacks
- RTOS integration
- Customized board support package

Notice of Disclaimer

Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)

Receiver Buffer

The receiver includes buffers (FIFOs) in the datapath. This section gives the reasons for including the buffers and outlines their operation.

The receiver buffer is required for two reasons:

- *Clock correction* to accommodate the slight difference in frequency between the recovered clock RXRECCLK and the internal FPGA user clock RXUSRCLK
- *Channel bonding* to allow realignment of the input stream to ensure proper alignment of data being read through multiple transceivers

The receiver uses an *elastic buffer,* where "elastic" refers to the ability to modify the read pointer for clock correction and channel bonding.

Comma Detection

Word alignment is dependent on the state of comma detect bits. If comma detect is enabled, the transceiver recognizes up to two 10-bit preprogrammed characters. Upon detection of the character or characters, the comma detect output is driven high and the data is synchronously aligned. If a comma is detected and the data is aligned, no further alignment alteration takes place. If a comma is received and realignment is necessary, the data is realigned and an indication is given at the receiver interface. The realignment indicator is a distinct output.

The transceiver continuously monitors the data for the presence of the 10-bit character(s). Upon each occurrence of a 10-bit character, the data is checked for word alignment. If comma detect is disabled, the data is not aligned to any particular pattern. The programmable option allows a user to align data on comma+, comma–, both, or a unique user-defined and programmed sequence.

Clock Correction

RXRECCLK (the recovered clock) reflects the data rate of the incoming data. RXUSRCLK defines the rate at which the FPGA fabric consumes the data. Ideally, these rates are identical. However, since the clocks typically have different sources, one of the clocks will be faster than the other. The receiver buffer accommodates this difference between the clock rates. See Figure 12.

Nominally, the buffer is always half full. This is shown in the top buffer, Figure 12, where the shaded area represents buffered data not yet read. Received data is inserted via the write pointer under control of RXRECCLK. The FPGA fabric reads data via the read pointer under control of RXUSRCLK. The half full/half empty condition of the buffer gives a cushion for the differing clock rates. This operation continues indefinitely, regardless of whether or not "meaningful" data is being received. When there is no meaningful data to be received, the incoming data will consist of IDLE characters or other padding.

If RXUSRCLK is faster than RXRECCLK, the buffer becomes more empty over time. The clock correction logic corrects for this by decrementing the read pointer to reread a repeatable byte sequence. This is shown in the middle buffer, Figure 12, where the solid read pointer decrements to the value represented by the dashed pointer.

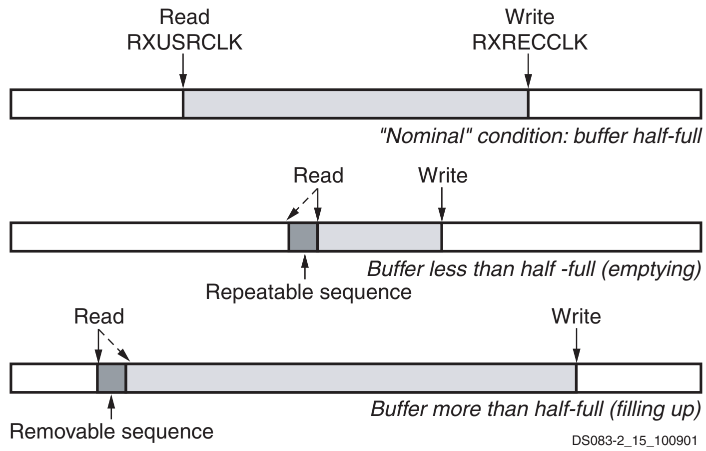

Figure 12: **Clock Correction in Receiver**

By decrementing the read pointer instead of incrementing it in the usual fashion, the buffer is partially refilled. The transceiver design will repeat a single repeatable byte sequence when necessary to refill a buffer. If the byte sequence length is greater than one, and if attribute CLK_COR_REPEAT_WAIT is 0, then the transceiver may repeat the same sequence multiple times until the buffer is refilled to the desired extent.

Similarly, if RXUSRCLK is slower than RXRECCLK, the buffer will fill up over time. The clock correction logic corrects for this by incrementing the read pointer to skip over a removable byte sequence that need not appear in the final FPGA fabric byte stream. This is shown in the bottom buffer, Figure 12, where the solid read pointer increments to the value represented by the dashed pointer. This accelerates the emptying of the buffer, preventing its overflow. The transceiver design will skip a single byte sequence when necessary to partially empty a buffer. If attribute CLK_COR_REPEAT_WAIT is 0, the transceiver may also skip two consecutive removable byte sequences in one step to further empty the buffer when necessary.

These operations require the clock correction logic to recognize a byte sequence that can be freely repeated or omitted in the incoming data stream. This sequence is generally an IDLE sequence, or other sequence comprised of special values that occur in the gaps separating packets of meaningful data. These gaps are required to occur sufficiently often to facilitate the timely execution of clock correction.

Channel Bonding

Some gigabit I/O standards such as Infiniband specify the use of multiple transceivers in parallel for even higher data rates. Words of data are split into bytes, with each byte sent over a separate channel (transceiver). See Figure 13.

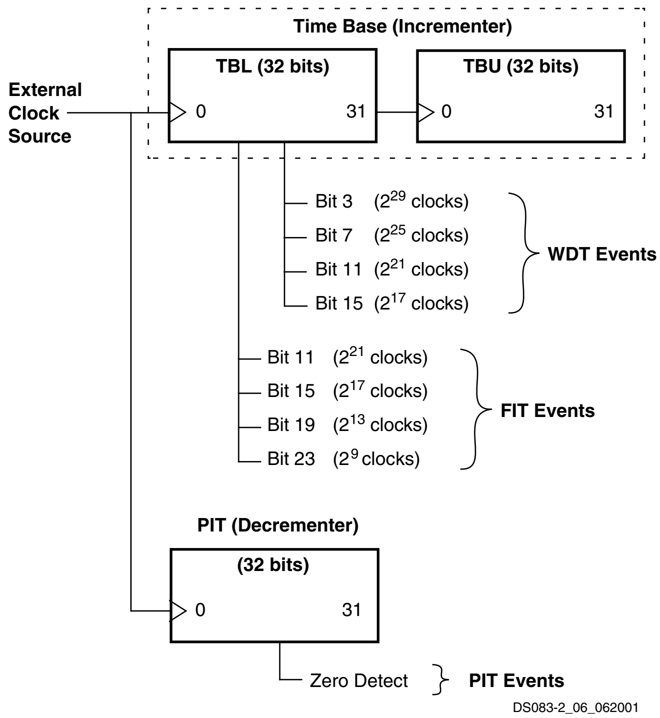

Figure 17: **Relationship of Timer Facilities to Base Clock**

Interrupts

The PPC405 provides an interface to an interrupt controller that is logically outside the PPC405 core. This controller combines the asynchronous interrupt inputs and presents them to the embedded core as a single interrupt signal. The sources of asynchronous interrupts are external signals, the JTAG/debug unit, and any implemented peripherals.

Debug Logic

All architected resources on the embedded PPC405 core can be accessed through the debug logic. Upon a debug event, the PPC405 core provides debug information to an external debug tool. Three different types of tools are supported depending on the debug mode: ROM monitors, JTAG debuggers, and instruction trace tools.

In internal debug mode, a debug event enables exception-handling software at a dedicated interrupt vector to take over the CPU core and communicate with a debug tool. The debug tool has read-write access to all registers and can set hardware or software breakpoints. ROM monitors typically use the internal debug mode.

In external debug mode, the CPU core enters stop state (stops instruction execution) when a debug event occurs. This mode offers a debug tool read-write access to all registers in the PPC405 core. Once the CPU core is in stop state, the debug tool can start the CPU core, step an instruction, freeze the timers, or set hardware or software break points. In addition to CPU core control, the debug logic is capable of writing instructions into the instruction cache, eliminating the need for external memory during initial board bring-up. Communication to a debug tool using external debug mode is through the JTAG port.

Debug wait mode offers the same functionality as external debug mode with one exception. In debug wait mode, the CPU core goes into wait state instead of stop state after a debug event. Wait state is identical to stop state until an interrupt occurs. In wait state, the PPC405 core can vector to an exception handler, service an interrupt and return to wait state. This mode is particularly useful when debugging real time control systems.

Real-time trace debug mode is always enabled. The debug logic continuously broadcasts instruction trace information to the trace port. When a debug event occurs, the debug logic signals an external debug tool to save instruction trace information before and after the event. The number of instructions traced depends on the trace tool.

Debug events signal the debug logic to stop the CPU core, put the CPU core in debug wait state, cause a debug exception or save instruction trace information.

Big Endian and Little Endian Support

The embedded PPC405 core supports big endian or little endian byte ordering for instructions stored in external memory. Since the PowerPC architecture is big endian internally, the ICU rearranges the instructions stored as little endian into the big endian format. Therefore, the instruction cache always contains instructions in big endian format so that the byte ordering is correct for the execution unit. This feature allows the 405 core to be used in systems designed to function in a little endian environment.

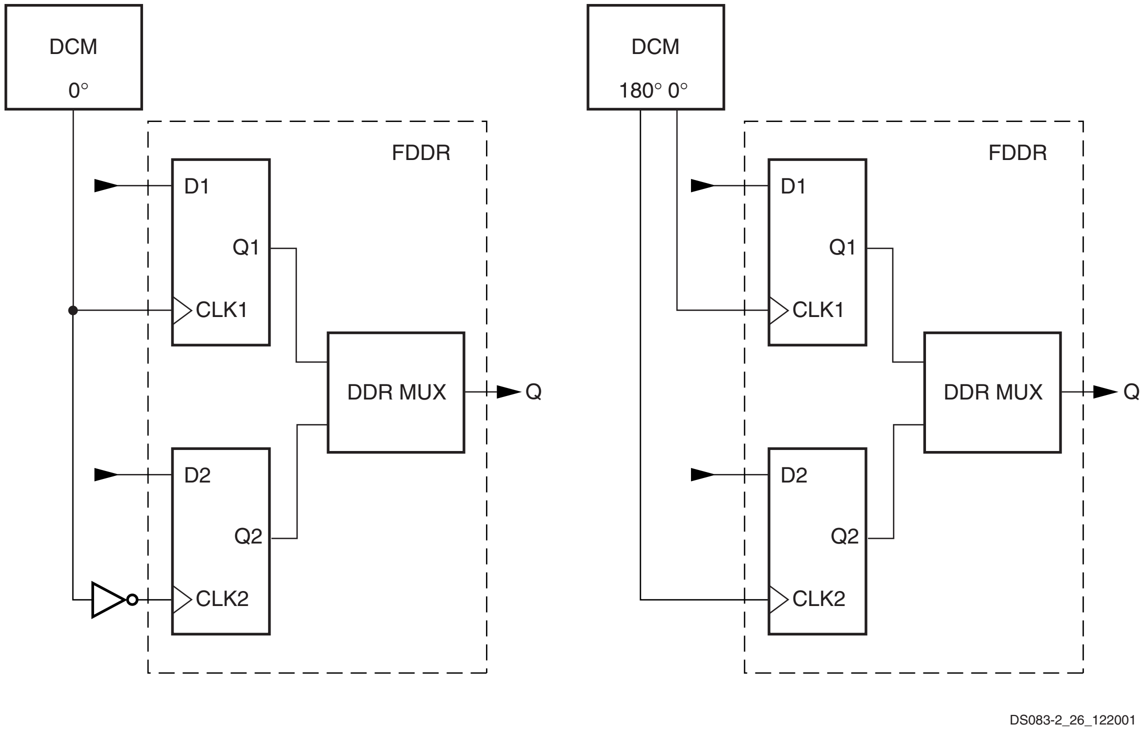

Figure 20: **Double Data Rate Registers**

This DDR mechanism can be used to mirror a copy of the clock on the output. This is useful for propagating a clock along the data that has an identical delay. It is also useful for multiple clock generation, where there is a unique clock driver for every clock load. Virtex-II Pro devices can produce many copies of a clock with very little skew.

Each group of two registers has a clock enable signal (ICE for the input registers, OCE for the output registers, and TCE for the 3-state registers). The clock enable signals are active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

Each IOB block has common synchronous or asynchronous set and reset (SR and REV signals). Two neighboring IOBs have a shared routing resource connecting the ICLK and OTCLK pins on pairs of IOBs. If two adjacent IOBs using DDR registers do not share the same clock signals on their clock pins (ICLK1, ICLK2, OTCLK1, and OTCLK2), one of the clock signals will be unroutable.

The IOB pairing is identical to the LVDS IOB pairs. Hence, the package pin-out table can also be used for pin assignment to avoid conflict.

SR forces the storage element into the state specified by the SRHIGH or SRLOW attribute. SRHIGH forces a logic 1. SRLOW forces a logic “0”. When SR is used, a second input (REV) forces the storage element into the opposite state. The reset condition predominates over the set condition. The initial state after configuration or global initialization state is defined by a separate INIT0 and INIT1 attribute. By default, the SRLOW attribute forces INIT0, and the SRHIGH attribute forces INIT1.

For each storage element, the SRHIGH, SRLOW, INIT0, and INIT1 attributes are independent. Synchronous or asynchronous set / reset is consistent in an IOB block.

All the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Each register or latch, independent of all other registers or latches, can be configured as follows:

- No set or reset
- Synchronous set
- Synchronous reset
- Synchronous set and reset
- Asynchronous set (preset)
- Asynchronous reset (clear)
- Asynchronous set and reset (preset and clear)

The synchronous reset overrides a set, and an asynchronous clear overrides a preset.

Refer to Figure 21.

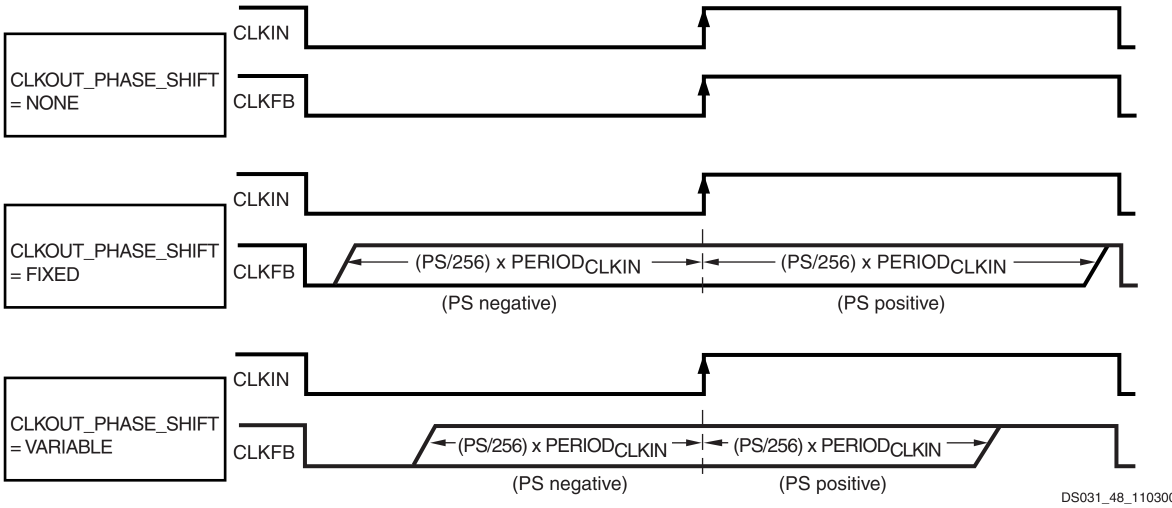

Figure 63: **Fine-Phase Shifting Effects**

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE\_SHIFT}/256) * \text{PERIOD}_{CLKIN}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If PERIOD_{CLKIN} = 2 * FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If PERIOD_{CLKIN} = FINE_SHIFT_RANGE, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $\text{PERIOD}_{CLKIN} \leq 0.5$ * FINE_SHIFT_RANGE, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 30. For actual values, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Routing

DCM and MGT Locations/Organization

Virtex-II Pro DCMs and serial transceivers (MGTs) are placed on the top and bottom of each block RAM and multiplier column in some combination, as shown in Table 31. The number of DCMs and RocketIO transceivers total twice the number of block RAM columns in the device. Refer to Figure 52, page 47 for an illustration of this in the XC2VP4 device.

Table 31: **DCM and MGT Organization**

Device	Block RAM Columns	DCMs	MGTs
XC2VP2	4	4	4
XC2VP4	4	4	4
XC2VP7	6	4	8
XC2VP20	8	8	8
XC2VPX20	8	8	8
XC2VP30	8	8	8
XC2VP40	10	8	12
XC2VP50	12	8	16
XC2VP70	14	8	20
XC2VPX70	14	8	20
XC2VP100	16	12	20

Place-and-route software takes advantage of this regular array to deliver optimum system performance and fast compile times. The segmented routing resources are essential to guarantee IP cores portability and to efficiently handle an incremental design flow that is based on modular implementations. Total design time is reduced due to fewer and shorter design iterations.

Hierarchical Routing Resources

Most Virtex-II Pro signals are routed using the global routing resources, which are located in horizontal and vertical routing channels between each switch matrix.

As shown in Figure 64, page 54, Virtex-II Pro has fully buffered programmable interconnections, with a number of resources counted between any two adjacent switch matrix rows or columns. Fanout has minimal impact on the performance of each net.

- The long lines are bidirectional wires that distribute signals across the device. Vertical and horizontal long lines span the full height and width of the device.
- The hex lines route signals to every third or sixth block away in all four directions. Organized in a staggered pattern, hex lines can only be driven from one end. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source).

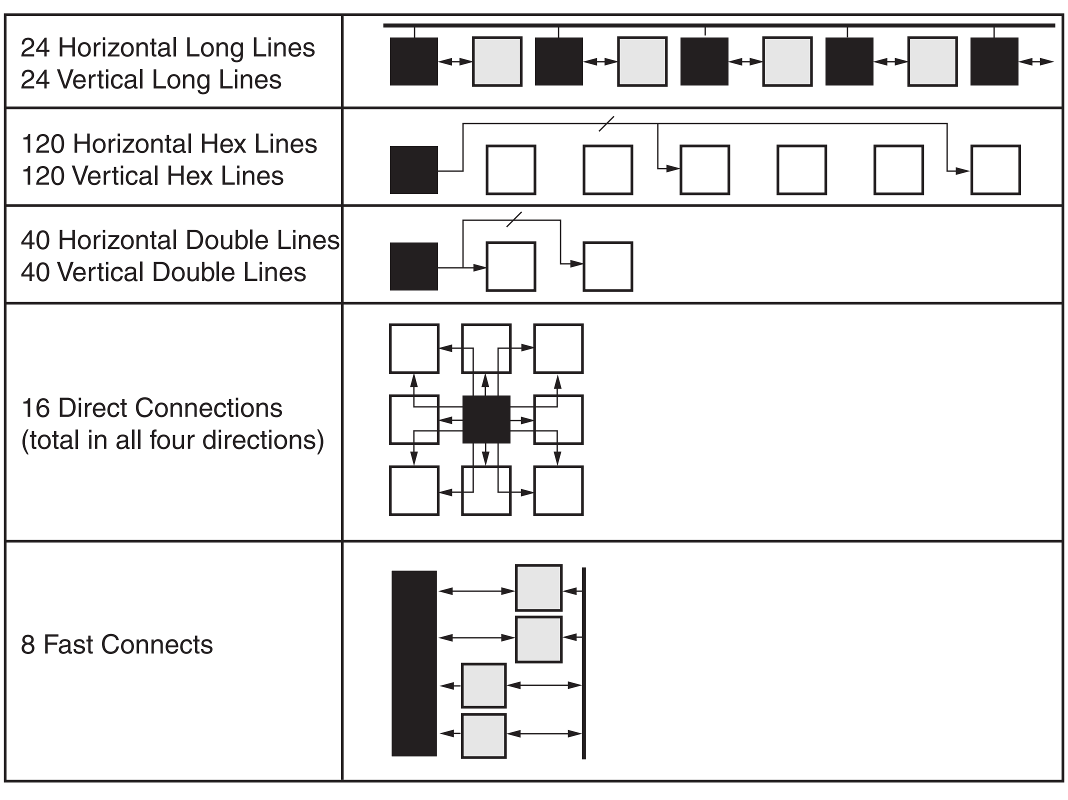

Figure 64: **Hierarchical Routing Resources**

Virtex-II Pro Performance Characteristics

This section provides the performance characteristics of some common functions and designs implemented in Virtex-II Pro devices. The numbers reported here are fully characterized worst-case values. Note that these values are subject to the same guidelines as Virtex-II Pro Switching Characteristics (speed files).

Table 13 provides pin-to-pin values (in nanoseconds) including IOB delays; that is, delay through the device from input pin to output pin. In the case of multiple inputs and outputs, the worst delay is reported.

Table 13: **Pin-to-Pin Performance**

Description	Device Used & Speed Grade	Pin-to-Pin Performance (with I/O Delays)	Units
Basic Functions:			
16-bit Address Decoder	XC2VP20FF1152-6	7.20	ns
32-bit Address Decoder	XC2VP20FF1152-6	8.08	ns
64-bit Address Decoder	XC2VP20FF1152-6	8.15	ns
4:1 MUX	XC2VP20FF1152-6	3.85	ns
8:1 MUX	XC2VP20FF1152-6	7.24	ns
16:1 MUX	XC2VP20FF1152-6	7.30	ns
32:1 MUX	XC2VP20FF1152-6	7.64	ns
Combinatorial (pad to LUT to pad)	XC2VP20FF1152-6	3.26	ns
Memory:			
Block RAM			
Pad to setup	XC2VP20FF1152-6	1.72	ns
Clock to Pad	XC2VP20FF1152-6	6.63	ns
Distributed RAM			
Pad to setup	XC2VP20FF1152-6	1.78	ns
Clock to Pad	XC2VP20FF1152-6	4.12	ns

Miscellaneous Timing Parameters

Table 61: **Miscellaneous Timing Parameters**

			Speed Grade			
Description	**Symbol**	**Constraints F_{CLKIN}**	**-7**	**-6**	**-5**	**Units**
Time Required to Achieve LOCK						
Using DLL outputs[1]	LOCK_DLL:					
	LOCK_DLL_60	> 60MHz	20.00	20.00	20.00	us
	LOCK_DLL_50_60	50 - 60 MHz	25.00	25.00	25.00	us
	LOCK_DLL_40_50	40 - 50 MHz	50.00	50.00	50.00	us
	LOCK_DLL_30_40	30 - 40 MHz	90.00	90.00	90.00	us
	LOCK_DLL_24_30	24 - 30 MHz	120.00	120.00	120.00	us
Using CLKFX outputs	LOCK_FX_MIN		10.00	10.00	10.00	ms
	LOCK_FX_MAX		10.00	10.00	10.00	ms
Additional lock time with fine phase shifting	LOCK_DLL_FINE_SHIFT		50.00	50.00	50.00	us
Fine Phase Shifting						
Absolute shifting range	FINE_SHIFT_RANGE		10.00	10.00	10.00	ns
Delay Lines						
Tap delay resolution	DCM_TAP_MIN		30.00	30.00	30.00	ps
	DCM_TAP_MAX		50.00	50.00	50.00	ps

Notes:
1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.

Frequency Synthesis

Table 62: **Frequency Synthesis**

Attribute	Min	Max
CLKFX_MULTIPLY	2	32
CLKFX_DIVIDE	1	32

Parameter Cross-Reference

Table 63: **Parameter Cross-Reference**

Libraries Guide	Data Sheet
DLL_CLKOUT_{MIN|MAX}_LF	CLKOUT_FREQ_{1X|2X|DV}_LF
DFS_CLKOUT_{MIN|MAX}_LF	CLKOUT_FREQ_FX_LF
DLL_CLKIN_{MIN|MAX}_LF	CLKIN_FREQ_DLL_LF
DFS_CLKIN_{MIN|MAX}_LF	CLKIN_FREQ_FX_LF
DLL_CLKOUT_{MIN|MAX}_HF	CLKOUT_FREQ_{1X|DV}_HF
DFS_CLKOUT_{MIN|MAX}_HF	CLKOUT_FREQ_FX_HF
DLL_CLKIN_{MIN|MAX}_HF	CLKIN_FREQ_DLL_HF
DFS_CLKIN_{MIN|MAX}_HF	CLKIN_FREQ_FX_HF

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
5	IO_L46N_5	W11			
5	IO_L46P_5	W10			
5	IO_L45N_5/VREF_5	AD9			
5	IO_L45P_5	AC9			
5	IO_L43N_5	AB9			
5	IO_L43P_5	AA9			
5	IO_L39N_5	Y9			
5	IO_L39P_5	W9			
5	IO_L37N_5	AF8			
5	IO_L37P_5	AE8			
5	IO_L09N_5/VREF_5	AB8			
5	IO_L09P_5	AA8			
5	IO_L07N_5/VREF_5	Y8			
5	IO_L07P_5	W8			
5	IO_L06N_5/VRP_5	AD7			
5	IO_L06P_5/VRN_5	AC7			
5	IO_L05_5/No_Pair	AB7			
5	IO_L03N_5/D4	AA7			
5	IO_L03P_5/D5	Y7			
5	IO_L02N_5/D6	AC6			
5	IO_L02P_5/D7	AB6			
5	IO_L01N_5/RDWR_B	AC5			
5	IO_L01P_5/CS_B	AB5			
6	IO_L01P_6/VRN_6	AE1			
6	IO_L01N_6/VRP_6	AD1			
6	IO_L02P_6	AD2			
6	IO_L02N_6	AC3			
6	IO_L03P_6	AC2			
6	IO_L03N_6/VREF_6	AC1			
6	IO_L05P_6	AB4			
6	IO_L05N_6	AA5			
6	IO_L06P_6	AB2			
6	IO_L06N_6	AB1			
6	IO_L23P_6	AA6	NC		

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	AVCCAUXRX21	AE7			
N/A	VTRXPAD21	AE6			
N/A	RXNPAD21	AF7			
N/A	RXPPAD21	AF6			
N/A	GNDA21	AD6			
N/A	TXPPAD21	AF5			
N/A	TXNPAD21	AF4			
N/A	VTTXPAD21	AE4			
N/A	AVCCAUXTX21	AE5			
N/A	M2	AD4			
N/A	M0	AF3			
N/A	M1	AE3			
N/A	TDI	D3			
N/A	VCCINT	G10			
N/A	VCCINT	G13			
N/A	VCCINT	G14			
N/A	VCCINT	G17			
N/A	VCCINT	J9			
N/A	VCCINT	J18			
N/A	VCCINT	K7			
N/A	VCCINT	K10			
N/A	VCCINT	K11			
N/A	VCCINT	K16			
N/A	VCCINT	K17			
N/A	VCCINT	K20			
N/A	VCCINT	L10			
N/A	VCCINT	L17			
N/A	VCCINT	N7			
N/A	VCCINT	N20			
N/A	VCCINT	P7			
N/A	VCCINT	P20			
N/A	VCCINT	T10			
N/A	VCCINT	T17			
N/A	VCCINT	U7			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L06N_1	E9			
1	IO_L06P_1	E8			
1	IO_L05_1/No_Pair	F8			
1	IO_L03N_1/VREF_1	D7			
1	IO_L03P_1	E7			
1	IO_L02N_1	C6			
1	IO_L02P_1	D6			
1	IO_L01N_1/VRP_1	A3			
1	IO_L01P_1/VRN_1	B3			
2	IO_L01N_2/VRP_2	C4			
2	IO_L01P_2/VRN_2	D3			
2	IO_L02N_2	A2			
2	IO_L02P_2	B1			
2	IO_L03N_2	C2			
2	IO_L03P_2	C1			
2	IO_L04N_2/VREF_2	D2			
2	IO_L04P_2	D1			
2	IO_L05N_2	E4			
2	IO_L05P_2	E3			
2	IO_L06N_2	E2			
2	IO_L06P_2	E1			
2	IO_L40N_2/VREF_2	F5	NC	NC	NC
2	IO_L40P_2	F4	NC	NC	NC
2	IO_L42N_2	F3	NC	NC	NC
2	IO_L42P_2	F2	NC	NC	NC
2	IO_L43N_2	G6	NC		
2	IO_L43P_2	G5	NC		
2	IO_L44N_2	G4	NC		
2	IO_L44P_2	G3	NC		
2	IO_L45N_2	F1	NC		
2	IO_L45P_2	G1	NC		
2	IO_L46N_2/VREF_2	H6	NC		
2	IO_L46P_2	H5	NC		
2	IO_L47N_2	H4	NC		
2	IO_L47P_2	H3	NC		
2	IO_L48N_2	H2	NC		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L87N_6/VREF_6	V33		
6	IO_L88P_6	V30		
6	IO_L88N_6	V31		
6	IO_L89P_6	V24		
6	IO_L89N_6	V25		
6	IO_L90P_6	V28		
6	IO_L90N_6	V29		
7	IO_L90P_7	U32		
7	IO_L90N_7	V32		
7	IO_L89P_7	U28		
7	IO_L89N_7	U29		
7	IO_L88P_7	U30		
7	IO_L88N_7/VREF_7	U31		
7	IO_L87P_7	T33		
7	IO_L87N_7	U33		
7	IO_L86P_7	U26		
7	IO_L86N_7	U27		
7	IO_L85P_7	T31		
7	IO_L85N_7	T32		
7	IO_L60P_7	R33		
7	IO_L60N_7	R34		
7	IO_L59P_7	U24		
7	IO_L59N_7	U25		
7	IO_L58P_7	R29		
7	IO_L58N_7/VREF_7	R30		
7	IO_L57P_7	P33		
7	IO_L57N_7	P34		
7	IO_L56P_7	T28		
7	IO_L56N_7	T29		
7	IO_L55P_7	P32		
7	IO_L55N_7	R32		
7	IO_L54P_7	P29		
7	IO_L54N_7	P30		
7	IO_L53P_7	T24		
7	IO_L53N_7	T25		
7	IO_L52P_7	N32		
7	IO_L52N_7/VREF_7	N33		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	TXNPAD23	AW36		
N/A	VTTXPAD23	AV36		
N/A	AVCCAUXTX23	AV35		
N/A	VCCINT	AH28		
N/A	VCCINT	M28		
N/A	VCCINT	AG27		
N/A	VCCINT	N27		
N/A	VCCINT	AF26		
N/A	VCCINT	P26		
N/A	VCCINT	AE25		
N/A	VCCINT	AD25		
N/A	VCCINT	AC25		
N/A	VCCINT	AB25		
N/A	VCCINT	AA25		
N/A	VCCINT	Y25		
N/A	VCCINT	W25		
N/A	VCCINT	V25		
N/A	VCCINT	U25		
N/A	VCCINT	T25		
N/A	VCCINT	R25		
N/A	VCCINT	AE24		
N/A	VCCINT	AD24		
N/A	VCCINT	T24		
N/A	VCCINT	R24		
N/A	VCCINT	AE23		
N/A	VCCINT	R23		
N/A	VCCINT	AE22		
N/A	VCCINT	R22		
N/A	VCCINT	AE21		
N/A	VCCINT	R21		
N/A	VCCINT	AE20		
N/A	VCCINT	R20		
N/A	VCCINT	AE19		
N/A	VCCINT	R19		
N/A	VCCINT	AE18		
N/A	VCCINT	R18		
N/A	VCCINT	AE17		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
1	IO_L30P_1		G13		
1	IO_L29N_1		K13		
1	IO_L29P_1		J13		
1	IO_L28N_1		M13		
1	IO_L28P_1		L13		
1	IO_L27N_1/VREF_1		E12		
1	IO_L27P_1		D12		
1	IO_L26N_1		F12		
1	IO_L26P_1		G12		
1	IO_L25N_1		J12		
1	IO_L25P_1		H12		
1	IO_L21N_1		L12		
1	IO_L21P_1		K12		
1	IO_L20N_1		C11		
1	IO_L20P_1		C10		
1	IO_L19N_1		F11		
1	IO_L19P_1		E11		
1	IO_L09N_1/VREF_1		J11		
1	IO_L09P_1		H11		
1	IO_L08N_1		D10		
1	IO_L08P_1		E10		
1	IO_L07N_1		G10		
1	IO_L07P_1		F10		
1	IO_L06N_1		J10		
1	IO_L06P_1		H10		
1	IO_L05_1/No_Pair		K11		
1	IO_L03N_1/VREF_1		D9		
1	IO_L03P_1		C9		
1	IO_L02N_1		E9		
1	IO_L02P_1		F9		
1	IO_L01N_1/VRP_1		H9		
1	IO_L01P_1/VRN_1		G9		
2	IO_L01N_2/VRP_2		C5		
2	IO_L01P_2/VRN_2		C6		
2	IO_L02N_2		E7		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	VCCO_5		AH22		
6	VCCO_6		AU38		
6	VCCO_6		AP40		
6	VCCO_6		AL37		
6	VCCO_6		AJ39		
6	VCCO_6		AH29		
6	VCCO_6		AG34		
6	VCCO_6		AG29		
6	VCCO_6		AG28		
6	VCCO_6		AF29		
6	VCCO_6		AF28		
6	VCCO_6		AE40		
6	VCCO_6		AE29		
6	VCCO_6		AE28		
6	VCCO_6		AD29		
6	VCCO_6		AD28		
6	VCCO_6		AC38		
6	VCCO_6		AC35		
6	VCCO_6		AC29		
6	VCCO_6		AC28		
6	VCCO_6		AB29		
6	VCCO_6		AB28		
7	VCCO_7		AA29		
7	VCCO_7		AA28		
7	VCCO_7		Y38		
7	VCCO_7		Y35		
7	VCCO_7		Y29		
7	VCCO_7		Y28		
7	VCCO_7		W29		
7	VCCO_7		W28		
7	VCCO_7		V40		
7	VCCO_7		V29		
7	VCCO_7		V28		
7	VCCO_7		U29		
7	VCCO_7		U28		
7	VCCO_7		T34		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects XC2VP100
6	IO_L15P_6	AP39	
6	IO_L15N_6/VREF_6	AP40	
6	IO_L16P_6	AP36	
6	IO_L16N_6	AP37	
6	IO_L17P_6	AH31	
6	IO_L17N_6	AG31	
6	IO_L18P_6	AN41	
6	IO_L18N_6	AN42	
6	IO_L19P_6	AN40	
6	IO_L19N_6	AM40	
6	IO_L20P_6	AG34	
6	IO_L20N_6	AG35	
6	IO_L21P_6	AN37	
6	IO_L21N_6/VREF_6	AN38	
6	IO_L22P_6	AN36	
6	IO_L22N_6	AM36	
6	IO_L23P_6	AG32	
6	IO_L23N_6	AG33	
6	IO_L24P_6	AM41	
6	IO_L24N_6	AM42	
6	IO_L25P_6	AM38	
6	IO_L25N_6	AM39	
6	IO_L26P_6	AF35	
6	IO_L26N_6	AF36	
6	IO_L27P_6	AM37	
6	IO_L27N_6/VREF_6	AL36	
6	IO_L28P_6	AL41	
6	IO_L28N_6	AK41	
6	IO_L29P_6	AF32	
6	IO_L29N_6	AF33	
6	IO_L30P_6	AL39	
6	IO_L30N_6	AL40	
6	IO_L31P_6	AL37	
6	IO_L31N_6	AL38	
6	IO_L32P_6	AF31	
6	IO_L32N_6	AE31	
6	IO_L33P_6	AK39	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L33N_6/VREF_6	AK40	
6	IO_L34P_6	AK36	
6	IO_L34N_6	AK37	
6	IO_L35P_6	AE36	
6	IO_L35N_6	AE37	
6	IO_L36P_6	AJ41	
6	IO_L36N_6	AJ42	
6	IO_L37P_6	AJ40	
6	IO_L37N_6	AH40	
6	IO_L38P_6	AE34	
6	IO_L38N_6	AE35	
6	IO_L39P_6	AJ38	
6	IO_L39N_6/VREF_6	AH37	
6	IO_L40P_6	AJ36	
6	IO_L40N_6	AJ37	
6	IO_L41P_6	AE32	
6	IO_L41N_6	AE33	
6	IO_L42P_6	AH41	
6	IO_L42N_6	AH42	
6	IO_L43P_6	AH38	
6	IO_L43N_6	AH39	
6	IO_L44P_6	AD36	
6	IO_L44N_6	AC35	
6	IO_L45P_6	AH36	
6	IO_L45N_6/VREF_6	AG36	
6	IO_L46P_6	AG41	
6	IO_L46N_6	AG42	
6	IO_L47P_6	AD34	
6	IO_L47N_6	AC33	
6	IO_L48P_6	AG40	
6	IO_L48N_6	AF39	
6	IO_L49P_6	AG38	
6	IO_L49N_6	AG39	
6	IO_L50P_6	AD32	
6	IO_L50N_6	AD33	
6	IO_L51P_6	AG37	
6	IO_L51N_6/VREF_6	AF37	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	VCCINT	AG26	
N/A	VCCINT	AF26	
N/A	VCCINT	U26	
N/A	VCCINT	T26	
N/A	VCCINT	R26	
N/A	VCCINT	AG25	
N/A	VCCINT	T25	
N/A	VCCINT	AG24	
N/A	VCCINT	T24	
N/A	VCCINT	AG23	
N/A	VCCINT	T23	
N/A	VCCINT	AG22	
N/A	VCCINT	T22	
N/A	VCCINT	AG21	
N/A	VCCINT	T21	
N/A	VCCINT	AG20	
N/A	VCCINT	T20	
N/A	VCCINT	AG19	
N/A	VCCINT	T19	
N/A	VCCINT	AG18	
N/A	VCCINT	T18	
N/A	VCCINT	AH17	
N/A	VCCINT	AG17	
N/A	VCCINT	AF17	
N/A	VCCINT	U17	
N/A	VCCINT	T17	
N/A	VCCINT	R17	
N/A	VCCINT	AJ16	
N/A	VCCINT	AH16	
N/A	VCCINT	AG16	
N/A	VCCINT	AF16	
N/A	VCCINT	AE16	
N/A	VCCINT	AD16	
N/A	VCCINT	AC16	
N/A	VCCINT	AB16	
N/A	VCCINT	AA16	
N/A	VCCINT	Y16	